

Multilayer Power Inductor

CIG21L Series (2012/ EIA 0805)



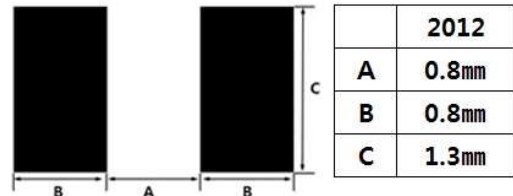
APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

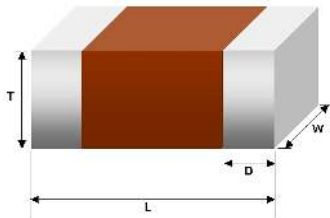
FEATURES

- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

RECOMMENDED LAND PATTERN



DIMENSION



| TYPE | Dimension [mm] | | | |
|------|----------------|----------|---------|-----------------|
| | L | W | T | D |
| 21 | 2.0±0.1 | 1.25±0.1 | 0.9±0.1 | 0.5+0.2 -0.3 |

DESCRIPTION

| Part no. | Size (inch/mm) | Inductance (μ H)@1MHz | DC Resistance(Ω) | Rated Current (A) Max. |
|--------------|-------------------|-------------------------------|------------------------------|---------------------------|
| CIG21LR47MNE | 0805/2012 | 0.47 \pm 20 % | 0.080 \pm 20 % | 1.30 |
| CIG21L1R0MNE | 0805/2012 | 1.0 \pm 20 % | 0.110 \pm 20 % | 1.15 |
| CIG21L1R2MNE | 0805/2012 | 1.2 \pm 20 % | 0.125 \pm 20 % | 1.10 |
| CIG21L1R5MNE | 0805/2012 | 1.5 \pm 20 % | 0.140 \pm 20 % | 1.05 |
| CIG21L2R2MNE | 0805/2012 | 2.2 \pm 20 % | 0.160 \pm 20 % | 0.95 |
| CIG21L3R3MNE | 0805/2012 | 3.3 \pm 20 % | 0.220 \pm 20 % | 0.80 |
| CIG21L4R7MNE | 0805/2012 | 4.7 \pm 20 % | 0.260 \pm 20 % | 0.75 |

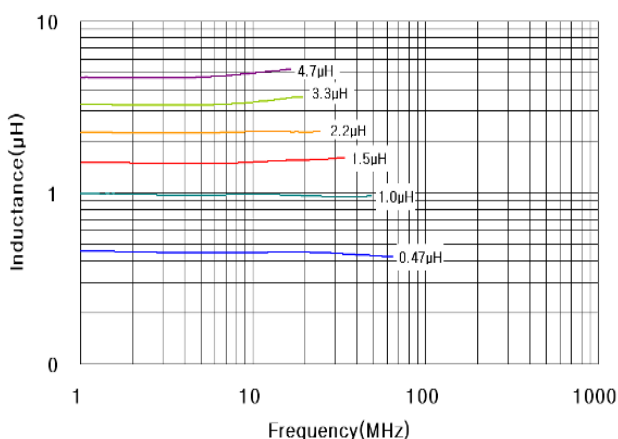
※Rated Current: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)

※Operating temperature range: -40 to +125℃ (Including self-temperature rise)

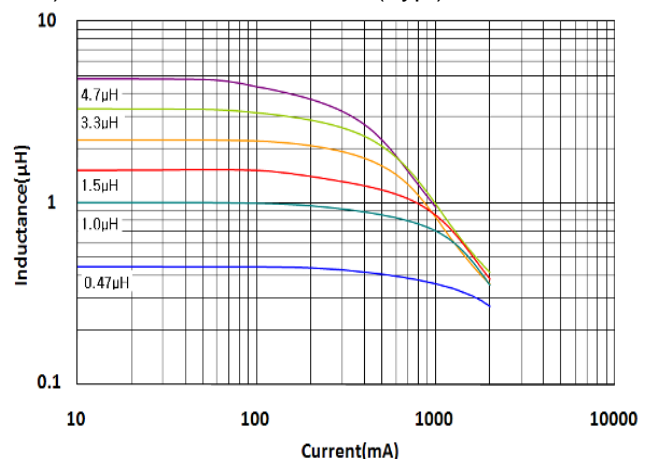
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



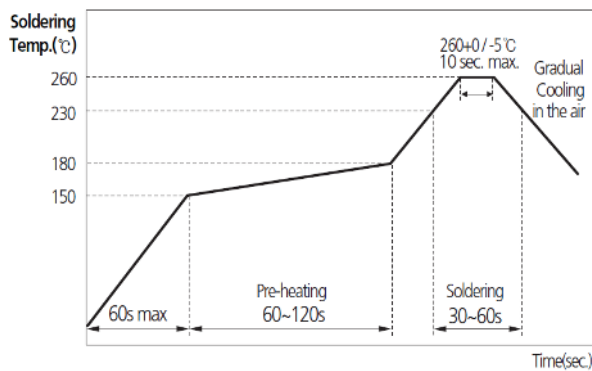
PRODUCT IDENTIFICATION

CI G 21 L 1R0 M N E
(1) (2) (3) (4) (5) (6) (7) (8)

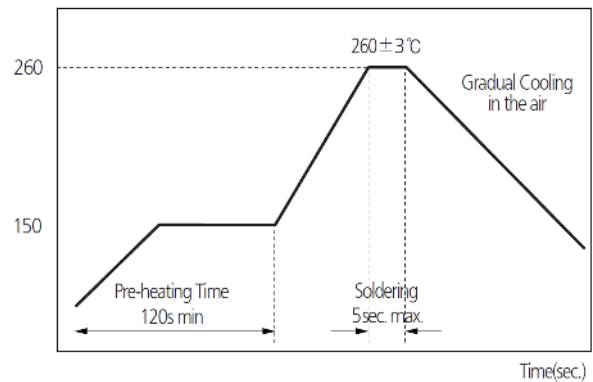
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (L:Low RDC Type)
- (5) Inductance (R47:0.47uH, 1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING




FLOW SOLDERING



PACKAGING

| Packaging Style | Quantity(pcs/reel) |
|-----------------|--------------------|
| Embossed Taping | 3,000 |

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